

Specifications

Designed to support applications such as: SOHO (ADSL Modems), LAN-on-Motherboard (LOM), Hub and Switches. Meets IEEE 802.3 specification.

Materials:

- Housing: Thermoplastic UL94V-0
- Contact/Shield: Copper Alloy
- Shield Plating: Nickel
- Contact Plating: Gold 6μ" min. in contact area
- Wave solder tip temperature: 265°C Max for 5 Sec Max

Electrical Specifications @25°C

Operating Temperature Range: 0°C to 70°C
Turn Ratio (±2%):

$$TX = 1CT:2.5, RX = 1CT:1$$

Inductance OCL:

$$140\mu H \text{ Min @ } 100KHz \text{ } 50mV$$

Insertion Loss:

$$-1.0dB \text{ Max @ } 1.0-10MHz$$

Return Loss:

$$-15dB \text{ Min @ } 1-10MHz$$

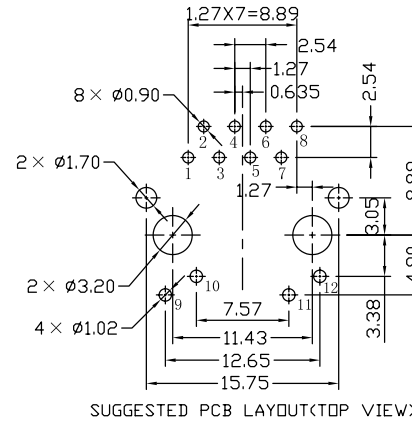
Cross Talk:

$$-30dB \text{ Min @ } 1-10MHz$$

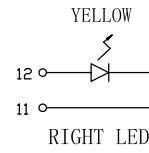
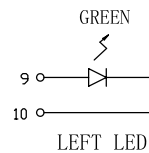
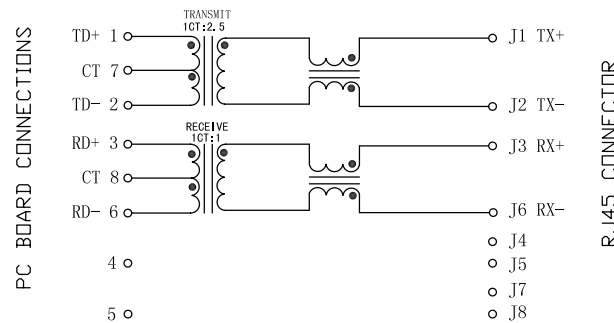
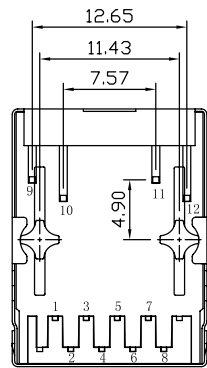
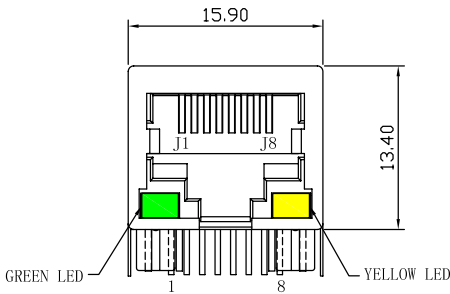
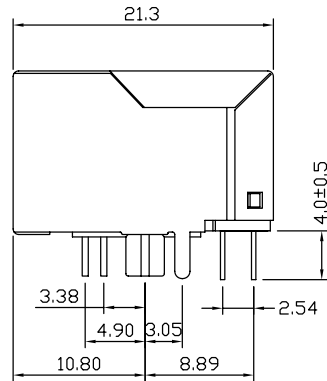
Common Mode Rejection:

$$-25dB \text{ Min @ } 5MHz$$

Hipot Test: 1500Vrms Min



SUGGESTED PCB LAYOUT (TOP VIEW)



* Contact Plating Option	Full Gold Plating	Gold Plated On Contact Area Tin Plated on Solder Area	Full Tin Plating
	G : Gold Flash G10: Gold 10u" G15: Gold 15u" G30: Gold 30u"	S: Gold Flash S10: Gold 10u" S15: Gold 15u" S30: Gold 30u"	T: Tin 100u"

General Tolerance	
.X ± 0.30	Angles: ±1°
.XX ± 0.20	
.XXX ± 0.05	
Units : mm	